

Title (en)

COMPOSITION AND PROCESS FOR TREATING METAL SURFACES

Title (de)

ZUSAMMENSETZUNG UND VERFAHREN ZUM BEHANDELN VON METALLOBERFLÄCHEN

Title (fr)

COMPOSITION ET PROCEDE DE TRAITEMENT DE SURFACES METALLIQUES

Publication

EP 1165857 A4 20030813 (EN)

Application

EP 00916098 A 20000303

Priority

- US 0005766 W 20000303
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- US 14793299 P 19990809
- US 15817199 P 19991007

Abstract (en)

[origin: WO0052226A1] A metal substrate is provided with a coating that (i) provides substantial corrosion resistance, (ii) makes it possible to shape the substrate by roll forming and similar light cold forming operations without the need for any oil or wax lubricant, and (iii) has good adhesion to subsequently applied paint. This is achieved by coating the metal substrate surface with an aqueous liquid composition that contains acrylate polymer resin, wax, and hexavalent chromium and then drying this coating into place on the surface to produce the desired dry coating.

IPC 1-7

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IPC 8 full level

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Citation (search report)

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- [Y] US 5321061 A 19940614 - ANDERSON KARL P [US]
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- [E] WO 0035595 A1 20000622 - HENKEL CORP [US], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 1995, no. 05 30 June 1995 (1995-06-30)
- See references of WO 0052226A1

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